

## **Product and Process Change Notice**

PCN No.	PCN02996	PCN Date	1/22/2018	Effective Date	4/23/2018
Title	Qualification of ChipMOS as an Assembly Site for DFN small flag Package				

#### **Type: Major Change**

Everspin is adding ChipMOS as a qualified assembly site for the DFN small flag package for SPI interface products.

#### **Reason For Change**

To increase capacity and improve supply flexibility.

## **Affected Products**

Part Number	Description	Part Number	Description
MR20H40CDF	Industrial Temp.	MR20H40CDFR	Industrial Temp., T&R
MR25H40CDF	Industrial Temp.	MR25H40CDFR	Industrial Temp., T&R
MR25H40VDF	Extended Temp.	MR25H40VDFR	Extended Temp., T&R
MR25H40MDF	Automotive Grade 1	MR25H40MDFR	Automotive Grade 1, T&R
MR25H10CDF	Industrial Temp.	MR25H10CDFR	Industrial Temp., T&R
MR25H10MDF	Automotive Grade 1	MR25H10MDFR	Automotive Grade 1, T&R
MR25H256CDF	Industrial Temp.	MR25H256CDFR	Industrial Temp., T&R
MR25H256MDF	Automotive Grade 1	MR25H256MDFR	Automotive Grade 1, T&R
MR25H256ACDF	Industrial Temp.	MR25H256ACDFR	Industrial Temp., T&R
MR25H256AMDF	Automotive Grade 1	MR25H256AMDFR	Automotive Grade 1, T&R
MR25H256APDF	Automotive Grade 3	MR25H256APDFR	Automotive Grade 3, T&R
MR25H128ACDF	Industrial Temp.	MR25H128ACDFR	Industrial Temp., T&R
MR25H128APDF	Automotive Grade 3	MR25H128APDFR	Automotive Grade 3, T&R
MR25H128AMDF	Automotive Grade 1	MR25H128AMDFR	Automotive Grade 1, T&R

#### Impact on Form, Fit, Function, Quality or Reliability

No impact

#### **Proposed First Ship Date for Change:**

April 23, 2018

## **Key Material Differences**

	Site		
Material	ChipMos	Amkor	
Mold Compound	SUMITOMO EME-G631H	SUMITOMO EME-G700	
BLT1 Epoxy	Hitachi 4900GC	Sumitomo CRM-1085A	
BLT2 Epoxy	EM-710	Henkel ATB-120A DAF	
BLT3 Epoxy	Henkel QMI550	Henkel Ablebond 8900NC	

#### **Product Identifier**

Assembly site code = H for ChipMOS Taiwan

#### **Supplier Qual Plan Schedule and Results**

ChipMOS assembly line qualification is complete and all Everspin requirements met; a qualification report is available on request.



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## **Date Qualification Samples Are Available:**

Samples are generally available now but please request your specific part number to your Everspin Sales contact.

## **Acceptance of Change**

Everspin will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice.

Contact Information		Sample Information Samples	s Available Now	
Joe O'Hare Director, Product Marketing Everspin Technologies joe.ohare@everspin.com (512) 828-3357		Contact Everspin sales: <a href="http://www.everspin.com/contact-us-everspin-technologies">http://www.everspin.com/contact-us-everspin-technologies</a> If using the on-line sample request please refer to this PCN # to receive samples.		
Originator	Originator			
<u>Date</u> 1/22/2018  Title Marke		eting Director	Name Joe O'Hare	
Approval and Release				
<u>Date</u> <u>Title</u> 1/22/2018 Qualit		y Engineer	Name Paul Drobny	
Date         Title           1/22/2018         VP of state		Sales	<u>Name</u> Annie Flaig	
<u>Date</u> 1/22/2018		Operations	<u>Name</u> Norm Armour	